



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2020-11-16
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	giovanni giacopello	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SM6T30A	8HZJ*TWU030D	A	9941	2020-11-16
	Amount	UoM	Unit type	ST ECOPACK Grade
	98	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00298574	

Package Designator	Size	Nbr of instances	Shape	
Not Applicable	4.54,3.68,2.10	2	shape	
Comment	SMB CLIP (SOD 6 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Delegated Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	die	173
Lead	0.81	soft solder	8245

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	0.81	Soft solder	8245
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	0.808	Soft solder	920273

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	8HZJ*TWU030D					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.651	mg	supplier	die	Silicon(Si)	7440-21-3		1.573	mg	952757	16051
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.015	mg	9085	153
				supplier	metallisation	Gold(Au)	7440-57-5		0.009	mg	5451	92
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.017	mg	10297	173
				supplier	passivation	Silicon oxide	7631-86-9		0.009	mg	5451	92
				supplier	polymer coating	Durimide	proprietary		0.028	mg	16959	286
Leadframe & clip	M-004 Copper and its alloys	39.118	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		39.098	mg	999489	398959
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.004	mg	102	41
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.014	mg	358	143
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.002	mg	51	20
Soft solder	Solder	0.878	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	0.808	mg	920273	8245
				supplier	solder	Tin(Sn)	7440-31-5		0.044	mg	50114	449
				supplier	solder	Silver(Ag)	7440-22-4		0.022	mg	25057	224
				supplier	solder	dry flux residue	proprietary		0.004	mg	4556	41
Encapsulation	M-011 Other inorganic materials	54.620	mg	supplier	mold compound	Amorphous silica	7631-86-9		35.814	mg	655693	365449
				supplier	mold compound	Quartz	14808-60-7		10.924	mg	200000	111469
				supplier	mold compound	Phenol type resin	proprietary		2.185	mg	40004	22296
				supplier	mold compound	Phenolic resin	9003-35-4		5.462	mg	100000	55735
				supplier	mold compound	Bismuth trioxide	1304-76-3		0.038	mg	696	388
				supplier	mold compound	Antimony pentoxide	1314-60-9		0.027	mg	494	276
				supplier	mold compound	Carbon black	1333-86-4		0.164	mg	3003	1673
				supplier	mold compound	Chlorine residue	22537-15-1		0.006	mg	110	61
connections coating	Solder	1.733	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.733	mg	1000000	17684